

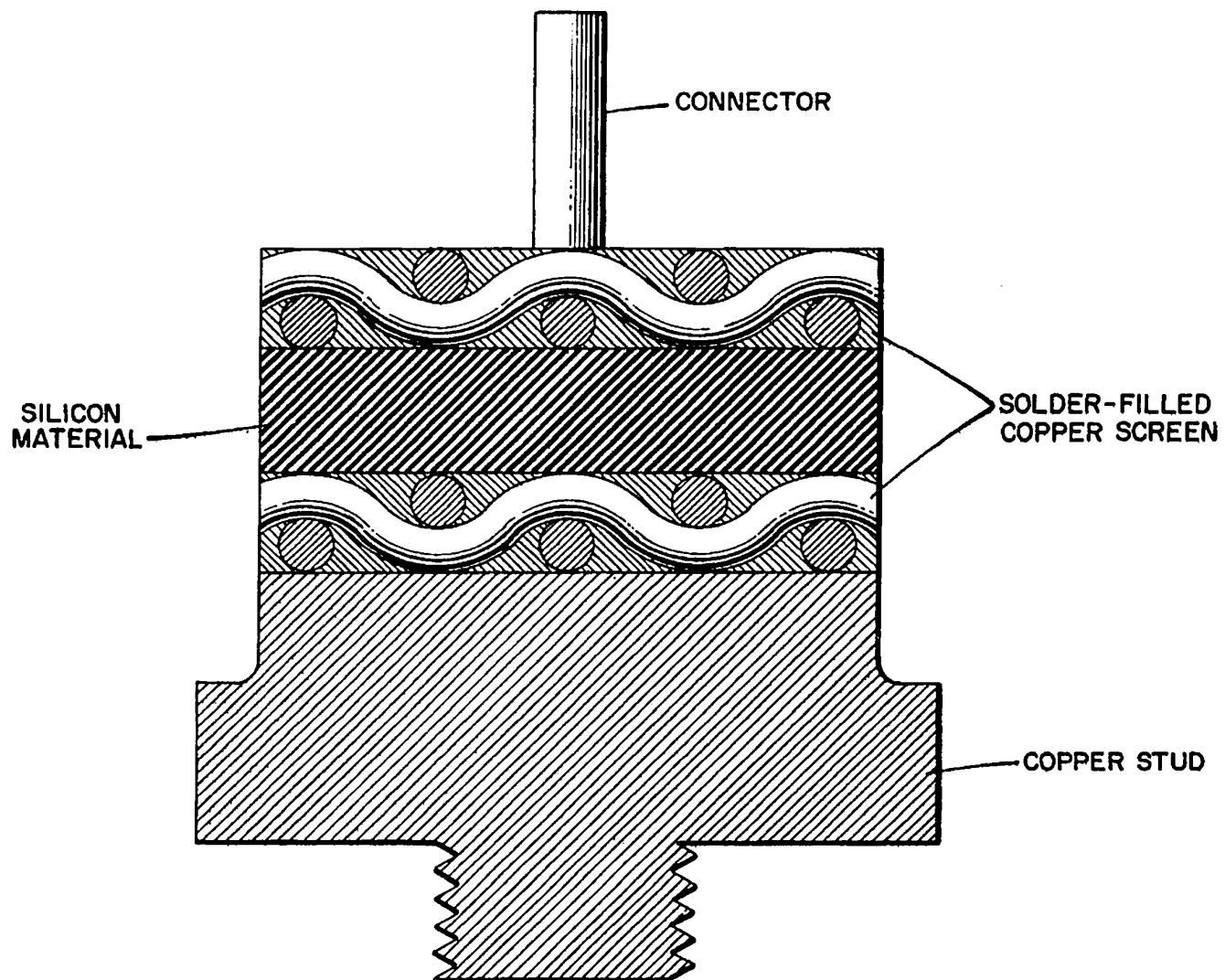
DOCUMENT-IDENTIFIER: NN600469

TITLE: Diode Heat Sink. April 1960.

----- KWIC -----

1p. SEE ORIGINAL FOR DIAGRAM. Where the silicon material of a diode is soldered directly to a heat sink stud, thermal fatigue produced by repeated on and off conditions often causes separation of the silicon material and stud.

- To overcome this condition, a nonrigid mounting is obtained by sandwiching the silicon material between, for example, layers of solder filled copper mesh or screen. These layers are then soldered to the silicon material and the connector and stud, respectively.



L Number	Hits	S arch Text	DB	Tim stamp
1	38	s lder near m sh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 13:33
2	59	(US-6171691-\$ or US-6270848-\$ or US-4529836-\$ or US-5540379-\$ or US-5617294-\$ or US-5779134-\$ or US-5842626-\$ or US-5090120-\$ or US-5304392-\$ or US-5429293-\$ or US-5192940-\$ or US-5000662-\$ or US-5403671-\$ or US-6226863-\$ or US-6432497-\$ or US-6122170-\$ or US-5877043-\$ or US-6096414-\$ or US-5502889-\$ or US-5735452-\$ or US-5310574-\$ or US-6221514-\$ or US-4416408-\$ or US-RE32086-\$ or US-5151777-\$ or US-5510174-\$).did. or (US-5545473-\$ or US-4654754-\$ or US-6335664-\$ or US-5909838-\$ or US-5088007-\$ or US-5136122-\$ or US-4129744-\$ or US-5072874-\$ or US-4993482-\$ or US-4934582-\$ or US-6280584-\$ or US-5591034-\$ or US-6350969-\$ or US-4711026-\$ or US-6262579-\$ or US-6297564-\$ or US-6307755-\$ or US-5986912-\$ or US-5786230-\$ or US-6083772-\$ or US-6081031-\$ or US-6046901-\$).did. or (US-20020084533-\$ or US-20020027294-\$ or US-20020012762-\$ or US-20020047038-\$).did. or (US-5088007-\$).did. or (US-4529836-\$ or SU-1581494-\$ or US-5842626-\$ or BR-9005457-\$ or US-5088007-\$ or US-5072874-\$).did. or (NN600469).tban.	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2002/08/23 13:34

3

22 ((US-6171691-\$ or US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ or  
US-5617294-\$ or US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
(solder near5 mesh)

USPAT; 2002/08/23  
US-PGPUB; 13:38  
EPO; JPO;  
DERWENT;  
IBM\_TDB

4

0 ((US-6171691-\$ r US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
(joint adj structure)

USPAT; 2002/08/23  
US-PGPUB; 13:39  
EPO; JPO;  
DERWENT;  
IBM\_TDB

5

22 ((US-6171691-\$ r US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
joint

USPAT; 2002/08/23  
US-PGPUB; 13:39  
EPO; JPO;  
DERWENT;  
IBM\_TDB

6

15 ((US-6171691-\$ r US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ or  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
(joint and (connection or interconnection))

USPAT; 2002/08/23  
US-PGPUB; 13:42  
EPO; JPO;  
DERWENT;  
IBM\_TDB

7

11 (((US-6171691-\$ r US-6270848-\$ r  
US-4529836-\$ or US-5540379-\$ r  
US-5617294-\$ or US-5779134-\$ or  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
(joint and (connection or interconnection)))  
and structure

USPAT; 2002/08/23  
US-PGPUB; 13:40  
EPO; JPO;  
DERWENT;  
IBM\_TDB



8

3 ((US-6171691-\$ or US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
((joint or (connection or interconnection or  
inteconnect)) near5 structure)

USPAT; 2002/08/23  
US-PGPUB; 13:47  
EPO; JPO;  
DERWENT;  
IBM\_TDB

9

56 ((US-6171691-\$ r US-6270848-\$ or  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ or  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
copper

USPAT; 2002/08/23  
US-PGPUB; 13:49  
EPO; JPO;  
DERWENT;  
IBM\_TDB

10

5 ((US-6171691-\$ or US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ or  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
heatsink

USPAT; 2002/08/23  
US-PGPUB; 13:49  
EPO; JPO;  
DERWENT;  
IBM\_TDB

11

20 ((US-6171691-\$ r US-6270848-\$ or  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ r US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
(heatsink or (heat adj sink))

USPAT; 2002/08/23  
US-PGPUB; 13:51  
EPO; JPO;  
DERWENT;  
IBM\_TDB

12

2 ((US-6171691-\$ r US-6270848-\$ r  
US-4529836-\$ r US-5540379-\$ r  
US-5617294-\$ or US-5779134-\$ r  
US-5842626-\$ or US-5090120-\$ or  
US-5304392-\$ or US-5429293-\$ or  
US-5192940-\$ or US-5000662-\$ or  
US-5403671-\$ or US-6226863-\$ or  
US-6432497-\$ or US-6122170-\$ or  
US-5877043-\$ or US-6096414-\$ or  
US-5502889-\$ or US-5735452-\$ or  
US-5310574-\$ or US-6221514-\$ or  
US-4416408-\$ or US-RE32086-\$ or  
US-5151777-\$ or US-5510174-\$).did. or  
(US-5545473-\$ or US-4654754-\$ or  
US-6335664-\$ or US-5909838-\$ or  
US-5088007-\$ or US-5136122-\$ or  
US-4129744-\$ or US-5072874-\$ or  
US-4993482-\$ or US-4934582-\$ or  
US-6280584-\$ or US-5591034-\$ or  
US-6350969-\$ or US-4711026-\$ or  
US-6262579-\$ or US-6297564-\$ or  
US-6307755-\$ or US-5986912-\$ or  
US-5786230-\$ or US-6083772-\$ or  
US-6081031-\$ or US-6046901-\$).did. or  
(US-20020084533-\$ or US-20020027294-\$ or  
US-20020012762-\$ or  
US-20020047038-\$).did. or  
(US-5088007-\$).did. or (US-4529836-\$ or  
SU-1581494-\$ or US-5842626-\$ or  
BR-9005457-\$ or US-5088007-\$ or  
US-5072874-\$).did. or (NN600469).tban.) and  
jumper

USPAT; 2002/08/23  
US-PGPUB; 13:54  
EPO; JPO;  
DERWENT;  
IBM\_TDB

13	15	((US-6171691-\$ or US-6270848-\$ r US-4529836-\$ r US-5540379-\$ r US-5617294-\$ r US-5779134-\$ r US-5842626-\$ or US-5090120-\$ or US-5304392-\$ or US-5429293-\$ or US-5192940-\$ or US-5000662-\$ or US-5403671-\$ or US-6226863-\$ or US-6432497-\$ or US-6122170-\$ or US-5877043-\$ or US-6096414-\$ or US-5502889-\$ or US-5735452-\$ or US-5310574-\$ or US-6221514-\$ or US-4416408-\$ or US-RE32086-\$ or US-5151777-\$ or US-5510174-\$).did. or (US-5545473-\$ or US-4654754-\$ or US-6335664-\$ or US-5909838-\$ or US-5088007-\$ or US-5136122-\$ or US-4129744-\$ or US-5072874-\$ or US-4993482-\$ or US-4934582-\$ or US-6280584-\$ or US-5591034-\$ or US-6350969-\$ or US-4711026-\$ or US-6262579-\$ or US-6297564-\$ or US-6307755-\$ or US-5986912-\$ or US-5786230-\$ or US-6083772-\$ or US-6081031-\$ or US-6046901-\$).did. or (US-20020084533-\$ or US-20020027294-\$ or US-20020012762-\$ or US-20020047038-\$).did. or (US-5088007-\$).did. or (US-4529836-\$ or SU-1581494-\$ or US-5842626-\$ or BR-9005457-\$ or US-5088007-\$ or US-5072874-\$).did. or (NN600469).tban.) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 13:54
-	0	("joint adj structure").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:19
-	7624	joint adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:25
-	0	(joint adj structure) and (mesh near solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:22
-	0	(joint adj structure) and (mesh near5 solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:22

-	4	(joint adj structure) and (mesh same sider)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:23
-	104	eytcheson	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:24
-	30	eytcheson near charles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:24
-	2	(joint adj structure) and (copper and strand and woven)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:27
-	2562	257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:27
-	3	257/773 and copper and strand	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:27
-	2055	copper and woven and strand	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:28
-	1154	(copper and woven and strand) and (joint or joining or connecting or connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:29
-	523	((copper and woven and strand) and (joint or joining or connecting or connection)) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:29
-	1	((((copper and woven and strand) and (joint or joining or connecting or connection)) and circuit) and heatsink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:29

-	113	((c pp r and w ven and strand) and (j int r j ining or connecting r c nn cti n)) and circuit) and s lder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:31
-	11	infiltrated near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:32
-	25	infiltrated near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:33
-	7624	joint adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:34
-	18	(joint adj structure) and (circuit adj assembly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:37
-	0	(joint adj structure) and (semiconductor adj device) and (circuit adj assembly) and (solder adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:39
-	0	solder adj infiltrated adj mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:40
-	0	solder near infiltrated near mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:40
-	0	solder near20 infiltrated near20 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:40
-	73	solder same infiltrated samemesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:40



-	2	solder same infiltrated same mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:41
-	74	solder same filled same mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:41
-	1	solder adj filled adj mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:41
-	3	solder near filled near mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:42
-	11	solder near5 filled near5 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:42
-	7006	screen adj mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:43
-	0	(screen adj mesh) near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:43
-	17	(screen adj mesh) near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:45
-	50	(screen adj mesh) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:46
-	6	((screen adj mesh) same solder) and (capacitor or heatsink or heat-sink or "heat sink")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:47
-	8	5779134.URPN.	USPAT	2002/08/15 11:47

-	239	circuit sam m sh same s ld r	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2002/08/15 11:48
-	11	circuit same mesh same solder same joint	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:50
-	31	circuit same mesh same solder same connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:51
-	28	(bonded or bonding) near5 (joint or connection) near5 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:53
-	0	(bonded or bonding) near5 (joint or connection) near5 mesh near5 solder near5 (circuit or device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:53
-	8	(bonded or bonding) same (joint or connection) same mesh same solder same (circuit or device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:55
-	2	(bonded or bonding) same (joint or connection) same copper same strand same solder same (circuit or device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:56
-	2	copper near strand near (bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:57
-	21	copper near5 strand near5 (bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:58
-	36	copper near10 strand near10 (bonded or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 11:59

-	2888	(joint or connection) and (circuit or device) and substrate and (capacitor or heatsink) and solder and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:04
-	80	((joint or connection) and (circuit or device) and substrate and (capacitor or heatsink) and solder and copper) and (fiber or strand) and (wire or wiring) and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:06
-	1092	((circuit or device) and (joint or connection) and (capacitor or heatsink)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:08
-	11	((circuit or device) and (joint or connection) and (capacitor or heatsink)).ti.) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:07
-	1135	((circuit or device) and (joint or connection) and (capacitor or heatsink)).ti,clm,ab.) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:09
-	35	((circuit or device) and (joint or connection) and (capacitor or heatsink)).ti,clm,ab.) and solder and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:16
-	2	5842626.URPN.	USPAT	2002/08/15 12:14
-	5	("3609471"   "4113578"   "4784310"   "5055914"   "5564617").PN.	USPAT	2002/08/15 12:14
-	8	5779134.URPN.	USPAT	2002/08/15 12:15
-	11	("4046442"   "4321423"   "4509096"   "4598308"   "4890196"   "5147210"   "5172031"   "5189261"   "5255431"   "5293301"   "5306670").PN.	USPAT	2002/08/15 12:15
-	36	(screen adjacent mesh) and thermal and (circuit or device or chip) and substrate and (capacitor or heatsink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:19
-	25075	(joint or connection) adjacent structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:21

-	13867	((j int r c nn cti n) adj structur ).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:22
-	567	((joint or connection) adj structure) and (mounting or mount or mounted or bonding or bonded or bond)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:22
-	0	((joint or connection) adj structure) and (mounting or mount or mounted or bonding or bonded or bond)).ti.) and (circuit or device or chip) and substrate and solder and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:23
-	13	((joint or connection) adj structure) and (mounting or mount or mounted or bonding or bonded or bond)).ti.) and substrate and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:24
-	2195	solder and copper and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:24
-	1846	(solder and copper and mesh) and (mounting or mount or mounted or bond or bonding or bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:25
-	1349	((solder and copper and mesh) and (mounting or mount or mounted or bond or bonding or bonded)) and (joint or connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:25
-	853	((solder and copper and mesh) and (mounting or mount or mounted or bond or bonding or bonded)) and (joint or connection)) and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:26
-	410	((solder and copper and mesh) and (mounting or mount or mounted or bond or bonding or bonded)) and (joint or connection)) and thermal) and coefficient	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:26
-	410	((solder and copper and mesh) and (mounting or mount or mounted or bond or bonding or bonded)) and (joint or connection)) and thermal) and coefficient) and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:26

-	236	((((s ld r and c pp r and m sh) and (mounting or mount r m unt d r b nd r b nding r b nd d)) and (joint r connection)) and thermal) and coefficient) and mesh) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:27
-	66	(((((((solder and copper and mesh) and (mounting or mount or mounted or bond or bonded or bonding)) and (joint or connection)) and thermal) and coefficient) and mesh) and semiconductor) and (heatsink or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:32
-	376	mesh and (capacitor or heatsink) and (mount or mounting or mounted or bond or bonded or bonding) and solder and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:34
-	17	(mesh and (capacitor or heatsink) and (mount or mounting or mounted or bond or bonded or bonding) and solder and copper) and strap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:34
-	8	((mesh and (capacitor or heatsink) and (mount or mounting or mounted or bond or bonded or bonding) and solder and copper) and strap) and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:34
-	7	(((mesh and (capacitor or heatsink) and (mount or mounting or mounted or bond or bonded or bonding) and solder and copper) and strap) and thermal) and coefficient	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:35
-	7630	joint adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:35
-	4	(joint adj structure) and (screen adj mesh)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:36
-	18	(joint adj structure) and (thermal adj coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:38
-	200	interconnect adj strap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:38

-	0	(interconnect adj strap) and (solder adj material)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:39
-	6	(interconnect adj strap) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:40
-	1	mesh near (solder adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:41
-	18	mesh near5 (solder adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:43
-	37	mesh near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:44
-	362	mesh near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:44
-	15	mesh near5 solder near5 copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:46
-	0	600469.URPN.	USPAT	2002/08/15 12:46
-	36	mesh near10 solder near10 copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:50
-	0	6171691.URPN.	USPAT	2002/08/15 12:50
-	0	6270848.URPN.	USPAT	2002/08/15 12:50
-	8	5617294.URPN.	USPAT	2002/08/15 12:51
-	0	6096414.URPN.	USPAT	2002/08/15 12:52

-	15	("4566990"   "4596670"   "4654754"   "4842911"   "4869954"   "4979074"   "5060114"   "5137959"   "5151777"   "5194480"   "5213868"   "5298791"   "5309320"   "5510174"   "5545473").PN.	USPAT	2002/08/15 12:52
-	8	5310574.URPN.	USPAT	2002/08/15 12:53
-	21785	solder same copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:54
-	2479	(solder same copper) and (heatsink or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:54
-	1593	((solder same copper) and (heatsink or capacitor)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:55
-	8	"I159" and (thermal or thermally)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:55
-	2060	(thermal or thermally) and (substrate) and (heatsink or capacitor) and (mounting or mounted or bonding or bonded) and copper and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:57
-	1911	((thermal or thermally) and (substrate) and (heatsink or capacitor) and (mounting or mounted or bonding or bonded) and copper and solder) and (joint or connection or couple or coupling)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:58
-	176	((((thermal or thermally) and (substrate) and (heatsink or capacitor) and (mounting or mounted or bonding or bonded) and copper and solder) and (joint or connection or couple or coupling)) and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 12:58
-	23	((((thermal or thermally) and (substrate) and (heatsink or capacitor) and (mounting or mounted or bonding or bonded) and copper and solder) and (joint or connection or couple or coupling)) and (mesh.ti,clm,ab.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:01
-	2972	(joint adj structure).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:03

-	1467	(screen adj mesh).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:03
-	0	((joint adj structure).ab.) and ((screen adj mesh).ab.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:03
-	1	((joint adj structure).ab.) and (screen adj mesh)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:04
-	0	((joint adj structure).ab.) and screen and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:05
-	0	((joint adj structure).ab,clm.) and screen and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:05
-	0	((joint adj structure).ab,clm.) and mesh and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:06
-	6	((joint adj structure)) and mesh and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:07
-	14	((connection adj structure)) and mesh and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:08
-	26	((mount or mounted or mounting or bond or bonded or bonding) near (capacitor or heatsink)) and mesh and solder and copper and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:13
-	0	((mount or mounted or mounting or bond or bonded or bonding) near (capacitor or heatsink)) and solder and (copper near (fiber or strand or woven)) and thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:15



-	2	((mount or mounted or mounting or bond or bonded or bonding) near (capacitor or heatsink)) and solder and (copper near (fiber or strand or woven))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:16
-	10	((mount or mounted or mounting or bond or bonded or bonding) near (capacitor or heatsink)) and solder and (copper near (fiber or strand or woven))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:18
-	10501	(copper near (fiber or strand or woven))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:18
-	87	(copper near (fiber or strand or woven)) near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:24
-	19	4,416,408	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 13:21
-	3	("5415176").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:01
-	0	("solder adj (infiltrated or impregnated or filled) adj mesh").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:03
-	1	solder adj (infiltrated or impregnated or filled) adj mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:06
-	3	solder near (infiltrated or impregnated or filled) near mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:07
-	6	solder near (infiltrated or impregnated or filled) near mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:09
-	25	4529836.URPN.	USPAT	2002/08/15 14:07

-	10	solder near3 (infiltrated or impregnated or filled) near3 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:10
-	10	solder near4 (infiltrated or impregnated or filled) near4 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:10
-	12	solder near5 (infiltrated or impregnated or filled) near5 mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:11
-	97	solder same (infiltrated or impregnated or filled) same mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:11
-	50	(solder same (infiltrated or impregnated or filled) same mesh) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:11
-	9	((solder same (infiltrated or impregnated or filled) same mesh) and copper) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:14
-	13	(woven adj copper) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:18
-	1	6280584.URPN.	USPAT	2002/08/15 14:16
-	14	("4911102"   "5759864"   "5833754"   "5885869"   "5894887"   "5935334"   "5980687"   "6015465"   "6055927"   "6198074"   "6270580"   "6273958"   "6280584"   "6332927"   "2001/0012697"   "2001/0054385").PN.	USPAT	2002/08/15 14:16
-	1	6280584.URPN.	USPAT	2002/08/15 14:16
-	7	("4338380"   "5011658"   "5737178"   "5794838"   "5886863"   "5998041"   "6134096").PN.	USPAT	2002/08/15 14:17
-	14	(woven near copper) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:22

-	75	(w v n sam c pp r) sam s lder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:19
-	7	((woven same copper) same solder) and (heatsink or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:20
-	19	(screen adj mesh) and (capacitor or heatsink) and solder and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:21
-	2	(strand near copper) near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:23
-	21	(strand near copper) near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:23
-	49	(strand near copper) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:25
-	20	(fiber near copper) near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:26
-	58	(fiber near copper) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:29
-	23	5088007.URPN.	USPAT	2002/08/15 14:28
-	5	(interwoven near copper) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:32
-	5	((interwoven or woven or fabric or fiber) near solder) and (heatsink or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:33

-	42	((int rw v n r w v n r fabric r fiber) near5 s ld r) and (h atsink r capacit r)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:35
-	19	((interwoven or woven or fabric or fiber) near10 solder) and (heatsink or capacitor) and (substrate near10 ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:39
-	0	((joint or connection or interconnection) adj structure) near5 (capacitor or transistor or heatsink) near5 (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:41
-	0	((joint or connection or interconnection) adj structure) near10 (capacitor or transistor or heatsink) near10 (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:42
-	2	((joint or connection or interconnection) adj structure) same (capacitor or transistor or heatsink) same (ceramic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:43
-	0	(joint or connection or interconnection) same (capacitor or transistor or heatsink) same (ceramic adj substrate) same solder same (woven or interwoven or fabric or fiber or strand)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:44
-	0	(joint or connection or interconnection) same (capacitor or transistor or heatsink) same (ceramic adj substrate) same solder same mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:45
-	4	((joint or connection or interconnection) same (capacitor or transistor or heatsink) same (ceramic adj substrate) same solder) and (interwoven or woven or fabric or strand or fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:45
-	76	(joint or connection or interconnection) same (capacitor or transistor or heatsink) same (ceramic adj substrate) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:46
-	445	(woven or interwoven or fabric or fiber or strand) and solder and (transistor or fet or capacitor or heatsink) and ((circuit or wiring) adj (assembly or board)) and (thermal r str ss r th rmally) and c effici nt	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:56

-	304	((w ven rint rw v n r fabric r fiber r strand) and ld r and (transist r r f t r capacit r r heatsink) and ((circuit r wiring) adj (assembly or board)) and (thermal or stress or thermally) and coefficient) and (connection or joint or interconnection) and (copper or aluminum) and substrate and (bonding or bonded or bond or mount or mounted or mounting)	USPAT; US-P PUB; EP ; JPO; DERWENT; IBM_TDB	2002/08/15 14:58
-	252	((((woven or interwoven or fabric or fiber or strand) and solder and (transistor or fet or capacitor or heatsink) and ((circuit or wiring) adj (assembly or board)) and (thermal or stress or thermally) and coefficient) and (connection or joint or interconnection) and (copper or aluminum) and substrate and (bonding or bonded or bond or mount or mounted or mounting)) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:58
-	52	(((((woven or interwoven or fabric or fiber or strand) and solder and (transistor or fet or capacitor or heatsink) and ((circuit or wiring) adj (assembly or board)) and (thermal or stress or thermally) and coefficient) and (connection or joint or interconnection) and (copper or aluminum) and substrate and (bonding or bonded or bond or mount or mounted or mounting)) and ceramic) and mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 14:59
-	0	6096414.URPN.	USPAT	2002/08/15 15:02
-	15	("4566990"   "4596670"   "4654754"   "4842911"   "4869954"   "4979074"   "5060114"   "5137959"   "5151777"   "5194480"   "5213868"   "5298791"   "5309320"   "5510174"   "5545473").PN.	USPAT	2002/08/15 15:02
-	0	solder adj filled adj copper adj screen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:07
-	0	solder near filled near copper near screen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:07
-	2	solder near5 filled near5 copper near5 screen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:08

-	5	s ld r n ar10 fill d near10 c pp r n ar10 scre n	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:08
-	1778	copper near (mesh or screen)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:10
-	0	copper near (mesh or screen) near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:11
-	5	copper near (mesh or screen) near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:12
-	61	copper near5 (mesh or screen) near5 solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:16
-	0	(joint adj structure) near (fet or capacitor or heatsink) near substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:20
-	0	((joint or interconnection or connection) adj structure) near (fet or capacitor or heatsink) near substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:22
-	16	(joint or interconnection or connection) near (fet or capacitor or heatsink) near substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:25
-	0	(joint or interconnection or connection) near5 (fet or capacitor or heatsink) near5 (ceramic adj substrate) near5 ((circuit or wiring) adj (board or assembly))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:27
-	64	(joint or interconnection or connection) same (fet or capacitor or heatsink) same (ceramic adj substrate) same ((circuit or wiring) adj (board or assembly))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:30

-	15	(j int rint rconnecti n r c nn cti n) sam (f t r capacit r r h atsink) sam (ceramic adj substrat ) sam ((circuit or wiring) adj (board or assembly)) same (bond or bonded or bonding)	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2002/08/15 15:34
-	10	(ceramic adj substrate) near ((joint or connection or interconnection or coupling) adj structure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:37
-	1790	solder near copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:37
-	0	(solder near copper) and (solder near copper adj (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:38
-	1	(solder near copper) and (solder near5 copper adj (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:39
-	0	(solder near copper) and (solder near copper near (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:39
-	10	(solder near copper) and (solder near copper near5 (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:39
-	11	(solder near copper) and (solder near5 copper near5 (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:42
-	61	(solder near5 (copper near5 (mesh or screen)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:43
-	14	((solder near5 (copper near5 (mesh or screen)))) and substrate and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:46

-	4	((solder near5 (capacitor or transistor or heatsink) and substrate and (capacitor or transistor or heatsink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:47
-	7010	screen adj mesh	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:48
-	20	(screen adj mesh) and substrate and (capacitor or fet or transistor or heatsink) and (bonding or bonded or bond) and (connecting or coupling or joint or connection) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:51
-	6	((screen adj mesh) and substrate and (capacitor or fet or transistor or heatsink) and (bonding or bonded or bond) and (connecting or coupling or joint or connection) and solder) and ((wiring or circuit) adj (board or assembly))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:54
-	84	jumper and ((circuit or wiring) adj (board or assembly)) and (fet or transistor or heatsink or capacitor) and (bonding or bonded or bond or couple or coupled or coupling or interconnection or connection or joint) and ceramic and substrate and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 15:58
-	23	(jumper and ((circuit or wiring) adj (board or assembly)) and (fet or transistor or heatsink or capacitor) and (bonding or bonded or bond or couple or coupled or coupling or interconnection or connection or joint) and ceramic and substrate and solder) and (woven or strand or strap or interwoven or fabric or fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:16
-	40	mesh same (infiltrated or impregnated or filled) same solder same material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:23
-	97	mesh same (infiltrated or impregnated or filled) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:31
-	2	(interconnect adj strap) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:34



-	9	(c pper near strap) and substrate and (transist r rf t r h atsink r capacit r) and (mounting r bonding r b nd r b nd d or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:40
-	12	(copper near2 strap) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:42
-	19	(copper near3 strap) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:46
-	5	(copper near3 jumper) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:48
-	150	(copper near solder) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 16:50
-	12	((copper near solder) and substrate and (transistor or fet or heatsink or capacitor) and (mounting or bonding or bond or bonded or coupled or coupling) and ((wiring or circuit) adj (assembly or board))) and (copper near solder).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/16 10:30
-	6901	kazan	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/16 10:30
-	0	kazan near restaurant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/16 10:30
-	1	kazan and restaurant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/16 10:36